

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Name MX150 BLD CS TERM GOLD 22AWG D WIND

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MX150 BLD CS TERM GOLD 22AWG D WIND	Assembly		100	0.364981
MX150 BLD CS TERM UNPLT 22AWG B WIND	Component		96.9913	0.354
HSM Copper Unplated	Material		96.9913	0.354
Copper	Substance	7440-50-8	95.1	0.347097
Nickel	Substance	7440-02-0	0.9699	0.00354
Tin	Substance	7440-31-5	0.8729	0.003186
Phosphorus	Substance	7723-14-0	0.0485	0.000177
Gold Plating	Material		0.2688	0.000981
Cobalt	Substance	7440-48-4	0.0007	0.000002
Nickel	Substance	7440-02-0	0.0007	0.000002
Gold	Substance	7440-57-5	0.2675	0.000976
Nickel Plating	Material		1.7809	0.0065
Nickel	Substance	7440-02-0	1.7807	0.006499

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Further Additives, not to declare	Substance	system	0.0002	6E-07
Tin Plating	Material		0.959	0.0035
Tin	Substance	7440-31-5	0.959	0.0035

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Not reviewed

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

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GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	High Copper Alloy (NB109)	*Note	10,000	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
silver	High Copper Alloy (NB109)	*Note	500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
copper	High Copper Alloy (NB109)	*Note	977,000	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

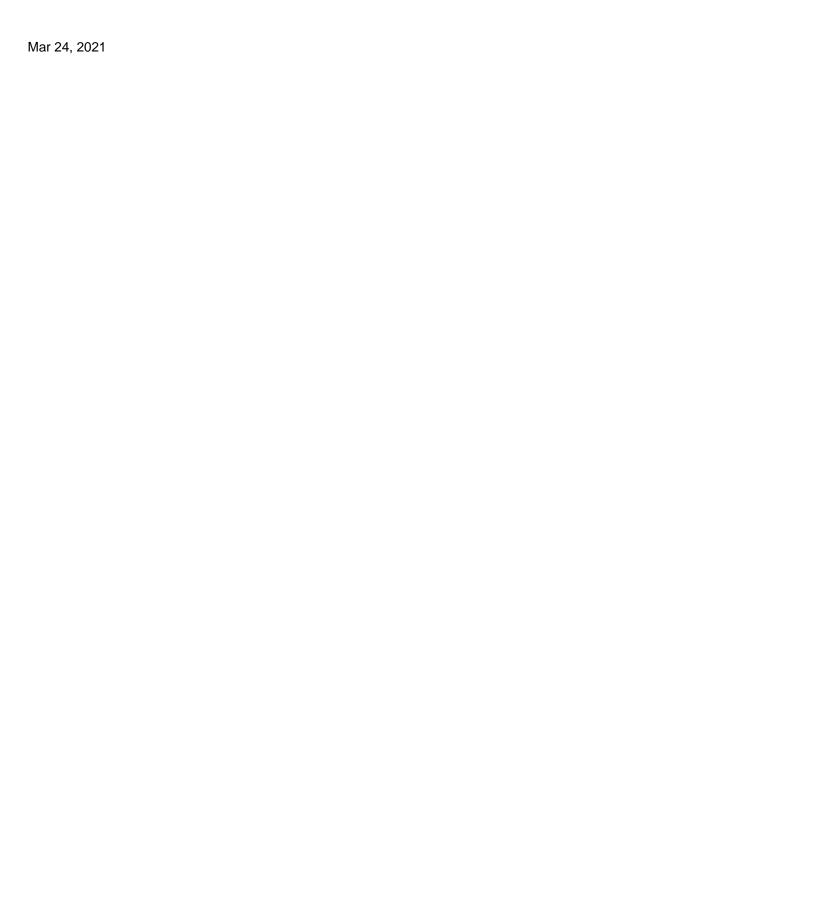
Exemptions

Part Name	Exemption
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
High Copper Alloy (NB109)	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

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